Document Number: S3G3037VS Preliminary Datasheet V1.0

GaN HEMT 50V, 370W,S band RF Power Transistor

Description

The S3G3037VS is a 370-watt capable, internally matched GaN HEMT, designed for pulsed amp applications within low end of S band. When used for full band like 2-3GHz etc, it can deliver >300W pulsed CW with high efficiency.

There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

It is recommended to use this device only at pulse condition, and power rating will be different according to different pulse width and duty cycle



Typical pulse Performance (On Innogration fixture with device soldered):

V_{DD} = 50 Volts, I_{DQ} = 10 mA, Pulse CW, Pulse width=20us, Duty cycle=10%.

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Freq	P1-	Р3	Р3	EFF(%)
(MHz)	Gain(dB)	(dBm)	(W)	@P3
2000	14.16	55.68	369.47	63.85
2100	15.48	56.11	408.42	63.63
2200	15.29	56.29	420.05	64.61
2300	14.81	56.12	409.22	66.21
2400	14.72	55.92	390.51	66.64
2500	14.05	55.62	364.78	65.59
2600	14.17	55.39	345.87	63.15
2700	14.19	55.46	351.79	62.11
2800	15.26	55.62	365.09	63.38
2900	15.48	55.58	361.30	65.38
3000	14.83	55.46	351.52	66.12

Applications and Features

- Suitable for broad band application in S band pulse amplifier applications.
- Thermally Enhanced Industry Standard Package
- · High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

■ Turning the device ON

- 1) Set VGS to the pinch--off (VP) voltage, typically –5 V
- 2) Turn on VDS to nominal supply voltage (50 V)
- 3) Increase VGS until IDS current is attained
- 4) Apply RF input power to desired level

■ Turning the device OFF

- 1) Turn RF power off
- 2) Reduce VGS down to VP, typically -5 V
- 3) Reduce VDS down to 0 V
- 4) Turn off VGS

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Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+200	Vdc
GateSource Voltage	V_{GS}	-8 to +0	Vdc
Operating Voltage	V _{DD}	0 to 55	Vdc
Maximum Forward Gate Current @ Tc = 25°C	Igmax	47	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case,Pout=370W @3GHz	RеJC	0.75	°C/W
by FEA 20us/10%, Tcase=85°C, 50 Vdc, IDQ =200 mA		0.75	

Table 3. Electrical Characteristics (TA = 25° C unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	V_{GS} =-8V; I_{DS} =47mA	V _{DSS}		200		V
Gate Threshold Voltage	$V_{DS} = 10V, I_{D} = 47mA$	V _{GS} (th)	-4		-2	V
Gate Quiescent Voltage	V _{DS} =50V, I _{DS} =340mA, Measured in Functional Test	$V_{GS(Q)}$		-3.22		V

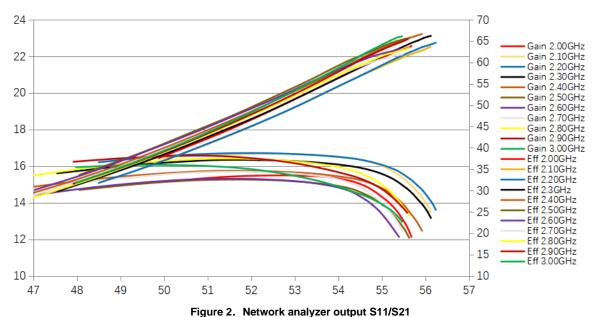
Load Mismatch (In Innogration Test Fixture, 50 ohm system): $V_{DD} = 50 \text{ Vdc}$, $I_{DQ} = 100 \text{ mA}$, f = 3000 MHz

VSWR 10:1 at 370W pulse CW Output Power	No Device Degradation
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TYPICAL CHARACTERISTICS

Figure 1. Power Gain and Drain Efficiency as Function of Pulse Output Power

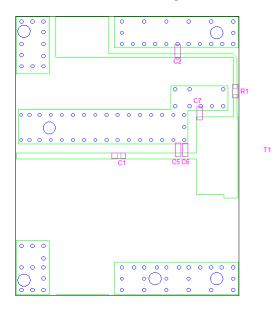


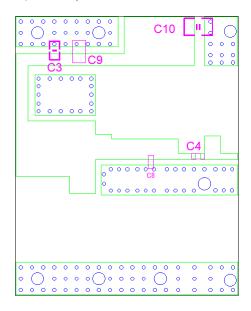
VDS=50V IDQ=350mA VGS=-3.2V

E5072A Network Analyzer 1 Active Ch/Trace 2 Response 3 Stimulus 4 Mkr/Analysis 5 Instr State Resize Log Mag 10.00 dB / Ref 0.000 dB [RT] Tr1 521 System 2.0000000 GHz 2.1000000 GHz 2.3000000 GHz 2.5000000 GHz 2.7000000 GHz 2.8000000 GHz 2.9000000 GHz 3.0000000 GHz 17.089 dB 17.370 dB 17.095 dB 16.475 dB 16.006 dB 16.929 dB 17.394 dB 17.491 dB 60.00 Print 40.00 Invert Image 30.00 20.00 Screen Imag 4 24 4 10.00 Misc Setup 0.000 Backlight -10.00Firmware -30.00 Revision Service Menu Tr2 S11 Log Mag 10.00 dB / Ref 0.000 dB [F1] 2.0000000 GHz +2.9587 dB 2.1000000 GHz -3.9299 dB 2.3000000 GHz -2.9789 dB 2.5000000 GHz -2.5009 dB 2.7000000 GHz -3.6504 dB 2.8000000 GHz -5.1727 dB 2.8000000 GHz -8.8373 dB 3.0000000 GHz -8.8519 dB 60.00 Help 50.00 40.00 Return 30.00 20.00 10.00 -10.00 -20.00 -30.00 40 00 Charle 10 MUI

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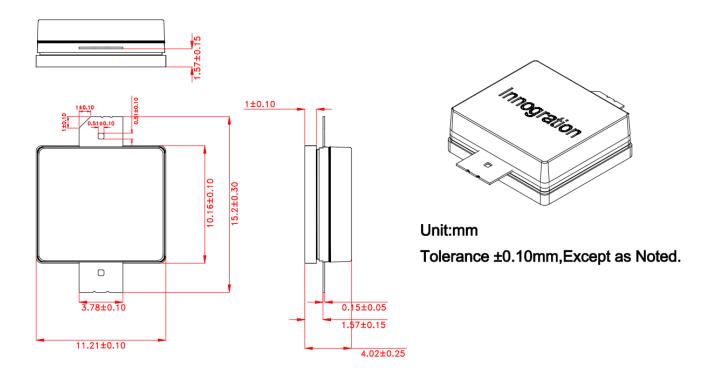
Figure 3. Test Circuit Component Layout





Part	Quantity	Description	Part Number	Manufacture
C1,C2,C3,C4	4	10pFHigh Q	251SHS100BSE	TEMEX
		Capacitor		
R1	1	10 Ω Power	ESR03EZPF100	ROHM
		Resistor		
C9,C10	2	10uF MLCC	GRM32EC72A106M	Murata
			E05	
C5	1	0.9pFHigh Q	251SHS0R9BSE	TEMEX
		Capacitor		
C6,C8	2	0.5pFHigh Q	251SHSOR5BSE	TEMEX
		Capacitor		
C7	1	0.3pFHigh Q	251SHS0R3BSE	TEMEX
		Capacitor		
T1	1	GaN	S3G3037VS	Innogration
		Transistor		

Package Dimensions (Unit:mm)



Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2025/5/7	Rev 1.0	Preliminary Datasheet

Application data based on LWH-25-17

Notice

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